FORM PTO-1595 (Modified)	RECORDATION FORM COV PATENTS ONLY	7975 CPI/L/B U.S. DEPARTMENT OF COMMERCE Patent and Trademark Office
To the Honorable Commissioner of Patents	and Trademarks: Please	record the attached original documents or copy thereof
1. Name of conveying party(ies):  Mei CHANG	<u>EXECUTION DATE</u> 6/27/2003	2. Name and address of receiving party(ies):  Name: <u>Applied Materials, Inc.</u> Internal Address: <u>Legal Affairs Department</u>
Additional name(s) of conveying part(ies) at  3. Nature of conveyance:  X Assignment C Merge		Street Address: <u>P.O. Box 450-A</u>
_	ge of Name	City: <u>Santa Clara</u> State <u>CA</u> Zip <u>95052</u>
Other		Additional Name(s) & address(es) attached? Γ Yes χ No
Execution Date: SEE ABOY5		
4. Application number(s) or patent Number(s):		
If this document is being filed together with a new application, the execution date of the application is:		
A. Patent Application No.(s)  Serial No. 10/443,648 - Filing Date  Additional Numbers attached? 1 Yes <u>x</u> No	; 5/22/2003	B. Patent No.(8)
5. Name and address of party to whom correctning document should be mailed:  Name: PATENT_COUNSEL  Internal Address: Applied Materials.  Legal Affairs Dept.  Street Address: P.O. Box 450-A  City: Santa Clara State:	<u>Inc.</u>	6. Total number of applications and patents involved:1  7. Total fee (37 CFR 3.41)\$40.00  Finctosed  x Authorized to be charged to deposit account  8. Deposit account number: 50-1074 (Attach duplicate copy of this page if paying by deposit account)
9. Statement and signature.  To the best of my knowledge and belief, the foregoing information is true and any attached copy is a true copy of the original document.  Robert W. Mulcahy, Reg. No. 25,436  Name of Person Signing  Signature  Date  OMB No. 0651-0011 (exp. 4/94)		
OND RO. 0031-0011 (GAP. 47747		

Mail documents to be recorded with the required cover sheet information to: Commissioner of Patents & Trademarks , Box Assignments Washington, D.C. 20231

FORMS\ASN-COV.LTR

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**PATENT REEL: 013965 FRAME: 0057** 

Case No. 5975/CPI/L/B/PS

## ASSIGNMENT FOR APPLICATION FOR PATENT

WHEREAS:

Names and Addresses of Inventors:

- 1) Mei Chang 12881 Corte de Arguello Saratoga, CA 95070
- 2) Ling Chen 784 Dartshire Way Sunnyvale, CA 94087

(hereinafter referred to as Assignors), have invented a certain invention entitled:

## NOBLE METAL LAYER FORMATION FOR COPPER FILM DEPOSITION

for which application for Letters Patent in the United States was filed on 5/22/2003, under Serial No. 10/443,648, executed on even date herewith; and

WHEREAS, Applied Materials, Inc., a corporation of the State of Delaware, having a place of business at 3050 Bowers Avenue, Santa Clara, California 95054 (hereinafter referred to as Assignee), is desirous of acquiring the entire right, title and interest in and to said application (hereinafter referred to as Application), and the invention disclosed therein (hereinafter referred to as Invention), and in and to all embodiments of the Invention, heretofore conceived, made or discovered by said Assignors, and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter referred to as Patents) thereon granted in any and all countries and groups of countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Assignors to have been received in full from said Assignee:

- Said Assignors hereby sell, assign, transfer and convey to Assignee the full and exclusive right, title and interest (a) in and to said Application and said Invention; (b) in and to all rights to apply for patents on said invention in any and all countries pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all Applications filed and any and all Patents granted on said Invention in any and all countries and groups of countries, including each and every Application filed and each and every Patent granted on any application which is a division, substitution, or continuation of said Application; and (d) in and to each and every reissue or extension of any of said Patents.
- Said Assignors hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest to said Invention herein conveyed in any and all countries and groups of countries. Such cooperation by said Assignors shall include prompt production of pertinent facts and documents, giving testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or

1 of 2

desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, divisional, continuing or additional applications covering said Invention; (d) for filing and prosecuting applications for reissuance of any of said Patents; (e) for interference or other priority proceedings involving said Invention; and (f) for legal proceedings involving said Invention and any application therefor and any Patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Assignors in providing such cooperation shall be paid for by said Assignee.

- 3. The term and covenants of this agreement shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Assignors, their respective heirs, legal representatives and assigns.
- 4. Said Assignors hereby warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

IN WITNESS WHEREOF, the said Assignors have executed and delivered this instrument to said Assignee on the dates indicated below.

1) July 27, 2003

MELCHAN

2) \_\_\_\_\_\_, 2003

TING CHEN

Case No. 5975/CPI/L/B/PS

## ASSIGNMENT FOR APPLICATION FOR PATENT

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1 of 2

**PATENT** REEL: 013965 FRAME: 0060 desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, divisional, continuing or additional applications covering said Invention; (d) for filing and prosecuting applications for reissuance of any of said Patents; (e) for interference or other priority proceedings involving said Invention; and (f) for legal proceedings involving said Invention and any application therefor and any Patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions, provided, however, that the expense incurred by said Assignors in providing such cooperation shall be paid for by said Assignee.

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- Said Assignors hereby warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

IN WITNESS WHEREOF, the said Assignors have executed and delivered this instrument to said Assignee on the dates indicated below.

, 2003 1)

**MEI CHANG** 

2)

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